

Section

MV Multifunction

Application

Field

Laboratory

**PRODUCT BENEFITS**

Tuning of the pitch of the tool

TOOL CAPACITY

Diameter 16 - 40 mm
0,630 - 1,575 inch

Non peelable semiconductor screen thickness capacity 0.4 - 1.4 mm / 0.026 - .06 inch

Insulation thickness capacity 7 mm / 0.28 inch

Chamfer angle on the non peelable semiconductor screen 14.5°

TOOL DIMENSIONS

Length 165 mm

Width 80 mm

Height 100 mm

Weight without box 1,03 Kg

Packaging Box

ALROC SAS

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Multifunction tool for outer sheath, bonded semiconductor and insulation

TO DO WHAT

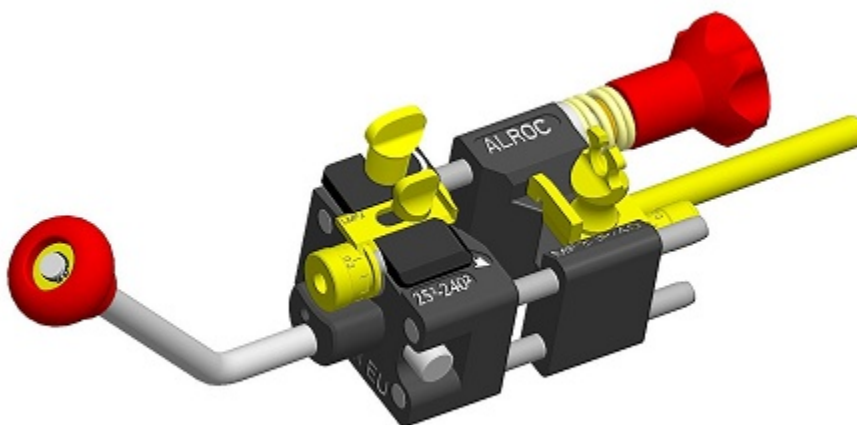
The MF3NP/60 tools enables the user to :

Remove the outer sheath (PE-PVC-PR) with a straight and neat cut.

Remove the bonded semiconductor with a chamfer and a minimum remaining length of semiconductor of 40 mm / 1.57 inch

Remove the insulation with a neat and straight cut

Silicon required for the removal of bonded semiconductor

**Spare part**

LMF2 - Spare blade for primary insulation

PCR - Quick set up right angled 45° handle

196855 - Straight handle M10

108098 - Clamping knob for blade

LASCR1 - Spare blade for bonded semiconductor

Associated tool

GRI-RTE - Scraper for residues of bonded semiconductor screen with protective case

LHA - Tool to chamfer insulation

MV cables Tools

MF3NP/40



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Non peelable semiconductor screen thickness capacity	Insulation thickness capacity	Chamfer angle on the non peelable semiconductor screen	Length	Width	Height	
MF3NP/40	16 - 40 mm 0,630 - 1,575 in	0.4 - 1.4 mm / 0.026 - .06 inch	7 mm / 0.28 inch	14.5°	165 mm 6,496 in	80 mm 3,150 in	100 mm 3,937 in	box
MF3NP/60	16 - 58 mm 0,630 - 2,283 in	0.4 - 1.4 mm / 0.026 - .06 inch	7 mm / 0.28 inch	14.5°	185 mm 7,283 in	90 mm 3,543 in	120 mm 4,724 in	box